

SEMICONDUCTOR DEVICE

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Abstract

PURPOSE: To assure high density packaging together with the improvement of reliability by superimposing on a substrate two or more of tape carrier packages, each of which is modified to realize the superimposed packaging of tape carrier packages.

CONSTITUTION: A upper tape carrier package 8a is one having a lead pattern 2 shown by A and a lower tape carrier package 8b is one having a lead pattern 2 shown by B. In A, a upper right end leads 2a are disposed in parallel to the remaining leads 2b. In B, the upper right end leads 2a are bent at a right angle. the packages 8a, 8b are superimposed on a packaging substrate 9, for packaging thereof. This improves packaging density compared with a situation where the packages 8a, 8b are provided in parallel to each other. Hereby, reliability is improved.

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